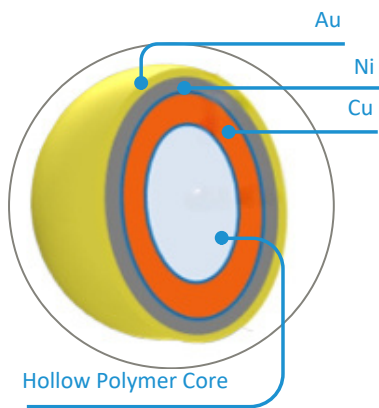


3 POLYMER CORE SOLDER BALLS

General informations



- Alternative to traditional non-collapsible lead solder balls
- Minimize mechanical stress
- Improve reliability and reparability
- Compatible with solder reflow according to IPC-J-STD-001
- Miniaturisation
- Flexible design w/ different possible coating
- Excellent corrosion resistance with extended shelf life
- Can be mounted using ICA or solder paste (lead free compatible)
- Controlled stand-off height (+/-5%)

Polymer core solder balls help improving the lifespan of electrical contact for assembling BGAs on a printed circuit board

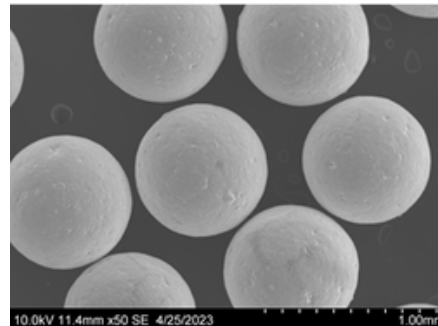
Technical Data

Ball size from 280 μm to 750 μm +/- 5%

Coating design* :
from 50 nm to 20 μm

Cu
Ni
Au

**Other possible configurations on demand*



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